



# MJ N-Channel Enhancement Mode Power MOSFET

## Description

The MJ30ND07AS uses advanced trench technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. It can be used in a wide variety of applications.

Application

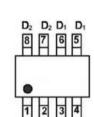
Power switching application

Uninterruptible power supply

Hard switched and high frequency circuits

### **General Features**

- V<sub>DS</sub> =30V,I<sub>D</sub> =7A
  R<sub>DS(ON)</sub> <23.5mΩ @ V<sub>GS</sub>=10V
  R<sub>DS(ON)</sub> <28mΩ @ V<sub>GS</sub>=4.5V
  R<sub>DS(ON)</sub> <34mΩ @ V<sub>GS</sub>=2.5V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current



S2 G2 S1

Marking and pin Assignment

G



SOP-8 top view

Schematic diagram

ackage Marking	and Orderin	ng Information			
Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
30ND07AS	MJ30ND07AS	SOP-8	Ø330mm	12mm	2500 units

## Absolute Maximum Ratings (TA=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	30	V
Gate-Source Voltage	Vgs	±12	V
Drain Current-Continuous	lD	7	А
Drain Current-Continuous(Tc =100°C)	ID(100℃)	4.95	А
Pulsed Drain Current	Ідм	30	А
Maximum Power Dissipation	PD	2	W
Operating Junction and Storage Temperature Range	Тј ,Тѕтс	-55 To 150	°C

#### Thermal Characteristic

Parameter	Symbol	Тур	Max	Unit
Thermal Resistance, Junction-to-Ambient (Note 2)	Reja	62.5	85	°C/W





## Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Uni
Off Characteristics	I	1		1		
Drain-Source Breakdown Voltage	BVDSS	V <sub>GS</sub> =0V I₀=250µA	30	-	-	v
Zero Gate Voltage Drain Current	loss	Vds=30V,Vgs=0V	-	-	1	μA
Gate-Body Leakage Current	lgss	Vds=±12V,Vds=0V	-	-	±100	nA
On Characteristics (Note 3)		1		1		1
Gate Threshold Voltage	VGS(th)	Vos=Vgs ,Id=250µA	0.6	0.9	1.2	V
		V <sub>GS</sub> =10V, I <sub>D</sub> =7A	-	20.5	23.5	mΩ
Drain-Source On-State Resistance	Rds(on)	Vgs=4.5V, Id=6A	-	22	28	mΩ
		Vgs=2.5V, Id=5A	-	26.7	34	mΩ
Forward Transconductance	<b>G</b> FS	Vds=5V,Id=7A	-	15	-	s
Dynamic Characteristics (Note 4)		I		1		1
Input Capacitance	Ciss		-	657.1	-	PF
Output Capacitance	Coss	V <sub>DS</sub> =15V,V <sub>GS</sub> =0V F=1.0MHz	-	65	-	PF
Reverse Transfer Capacitance	Crss		-	50	-	PF
Switching Characteristics (Note 4)		1		1		1
Turn-on Delay Time	t <sub>d(on)</sub>		-	5	-	nS
Turn-on Rise Time	tr	V₀₀=15V, R∟=2Ω	-	3	_	nS
Turn-Off Delay Time	td(off)	V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω	-	20	-	nS
Turn-Off Fall Time	tr		-	4	-	nS
Total Gate Charge	Qg		-	9.4	-	nC
Gate-Source Charge	Qgs	V <sub>DS</sub> =15V,I <sub>D</sub> =7A V <sub>GS</sub> =4.5V	-	1.1	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	2.4	-	nC
Drain-Source Diode Characteristics	I	<u> </u>	<u> </u>	1	L	1
Diode Forward Voltage (Note 3)	Vsd	V <sub>GS</sub> =0V,I <sub>S</sub> =7A	-	-	1.2	V
Diode Forward Current (Note 2)	ls		-	-	7	A

#### Notes:

(1) Repetitive Rating: Pulse width limited by maximum junction temperature.

② The value of R<sub>BJA</sub> is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C. The value in any given application depends on the user's specific board design.Surface Mounted on FR4 Board, t ≤ 10 sec. The current rating is based on the t ≤10s thermal resistance rating.

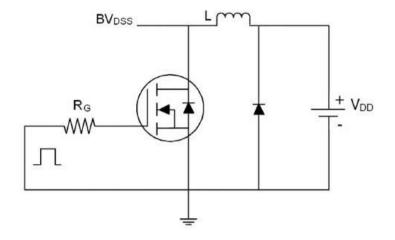
③ Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.

④ Guaranteed by design, not subject to production

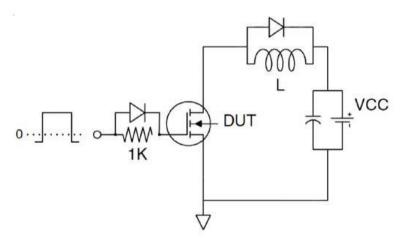




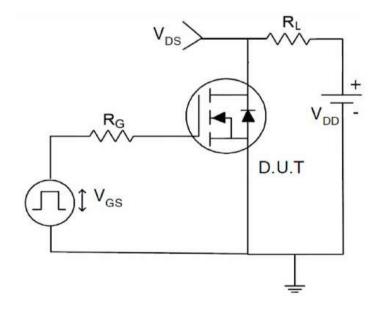
Test circuit







Gate charge test Circuit



Switch Time Test Circuit





## N-channel Typical Electrical and Thermal Characteristics (Curves)

RoHS

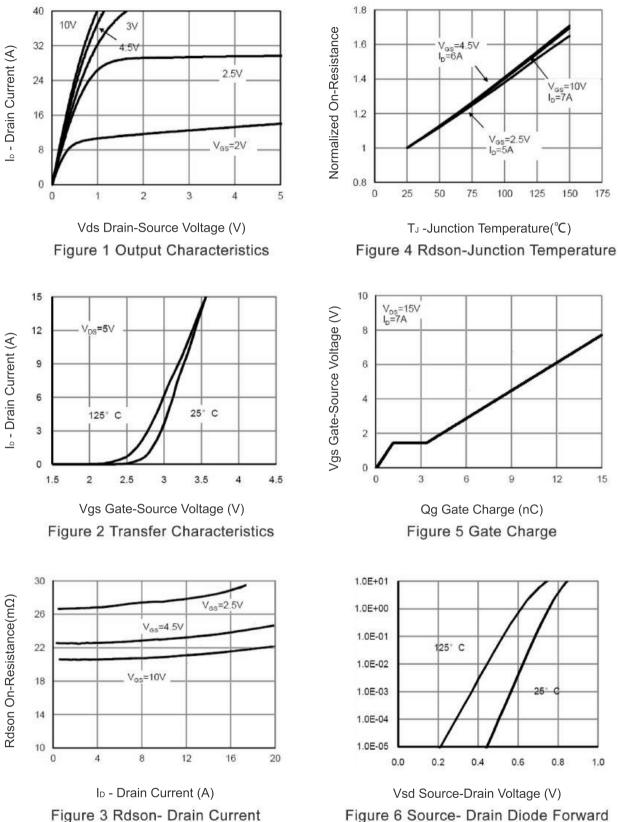
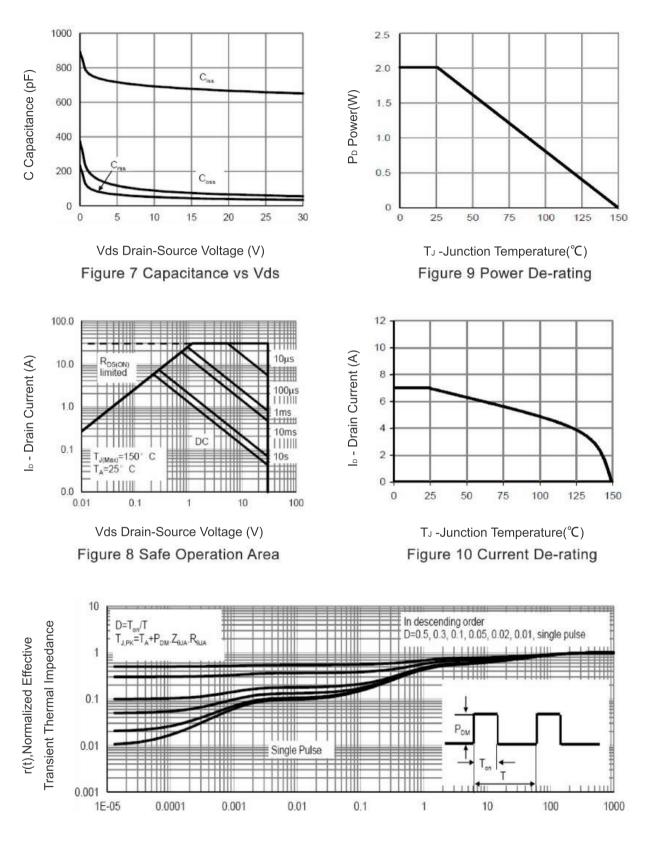


Figure 6 Source- Drain Diode Forward





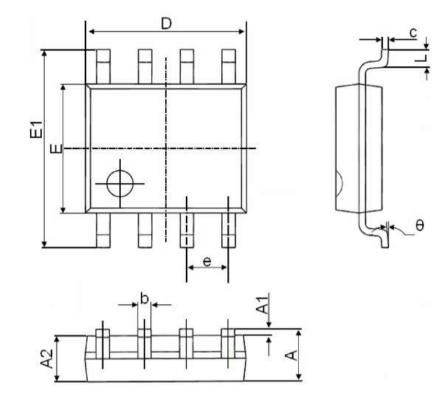


Square Wave Pluse Duration(sec) Figure 11 Normalized Maximum Transient Thermal Impedance





## SOP-8 Package Information



Cumuland	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
c	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270	(BSC)	0.050	(BSC)	
L	0.400	1.270	0.016	0.050	
e	0°	8°	0°	8°	





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